



## HE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: Keith E. FOGEL et al. CONFIRM. NO.: 6557

SERIAL NO.: 10/815,103 ART UNIT: 2826

FILED: 03/31/2004 EXAMINER: L. ANDUJAR

TITLE: INTERCONNECTIONS FOR FLIP-CHIP USING LEAD-FREE

SOLDERS AND HAVING REACTION BARRIER LAYERS

ATTORNEY DOCKET NO.: YOR920030190US1

Mail Stop Issue Fee Commissioner for Patents

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## ADDITIONAL INFORMATION DISCLOSURE STATEMENT, CERTIFICATION UNDER 37 C.F.R. 1.97(e) (1) AND FEE UNDER 37 C.F.R. 1.17(p)

In accordance with the duty of disclosure, applicants call to the attention of the Examiner the documents cited attached form PTO-1449 (Substitute). the respectfully requested that the Examiner consider these documents, and make them of record.

I hereby certify that each item of information cited herein was first cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this paper.

Please charge the fee of \$180 required by 37 C.F.R. 1.17(p) to deposit account 50-0510. A duplicate of this page is enclosed.

Respectfully submitted,

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## Certificate of Mailing

hereby certify that this correspondence is deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

February 28, 2008

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